

- Three Bidirectional Transceivers
- Driver Meets or Exceeds the Requirements of ANSI EIA/TIA-422-B and RS-485 and ITU Recommendation V.11
- Two Skew Limits Available
- Designed to Operate Up to 20 Million Data Transfers per Second (FAST-20 SCSI)
- High-Speed Advanced Low-Power Schottky Circuitry
- Low Pulse Skew . . . 5 ns Max
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Features Independent Driver Enables and Combined Receiver Enables
- Wide Positive and Negative Input/Output Bus Voltages Ranges
- Driver Output Capacity . . .  $\pm 60$  mA
- Thermal Shutdown Protection
- Driver Positive- and Negative-Current Limiting
- Receiver Input Impedances . . . 12 k $\Omega$  Min
- Receiver Input Sensitivity . . .  $\pm 300$  mV Max
- Receiver Input Hysteresis . . . 60 mV Typ
- Operates From a Single 5-V Supply
- Glitch-Free Power-Up and Power-Down Protection

DW OR J PACKAGE  
(TOP VIEW)

1R	1	20	1B
1DE	2	19	1A
1D	3	18	RE
GND	4	17	CDE
GND	5	16	V <sub>CC</sub>
2R	6	15	2B
2DE	7	14	2A
2D	8	13	3B
3R	9	12	3A
3DE	10	11	3D

## description

The SN75ALS171 and the SN75ALS171A triple differential bus transceivers are monolithic integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines, and each driver meets ANSI Standards EIA/TIA-422-B and RS-485 and both the drivers and receivers meet ITU Recommendation V.11. The SN75ALS171A is designed for FAST-20 SCSI and can transmit or receive data pulses as short as 30 ns with a maximum skew of 5 ns.

The SN75ALS171 and the SN75ALS171A operate from a single 5-V power supply. The drivers and receivers have individual active-high and active-low enables, respectively, which can be externally connected together to function as a direction control. The driver differential output and the receiver differential input pairs are connected internally to form differential input/output (I/O) bus ports that are designed to offer minimum loading to the bus when the driver is disabled or V<sub>CC</sub> is at 0 V. These ports feature wide positive and negative common-mode voltage ranges making the device suitable for party-line applications.

The SN75ALS171 and the SN75ALS171A are characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

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## Function Tables

### EACH DRIVER

INPUT D	ENABLES		OUTPUTS	
	DE	CDE	A	B
H	H	H	H	L
L	H	H	L	H
X	L	X	Z	Z
X	X	L	Z	Z

### EACH RECEIVER

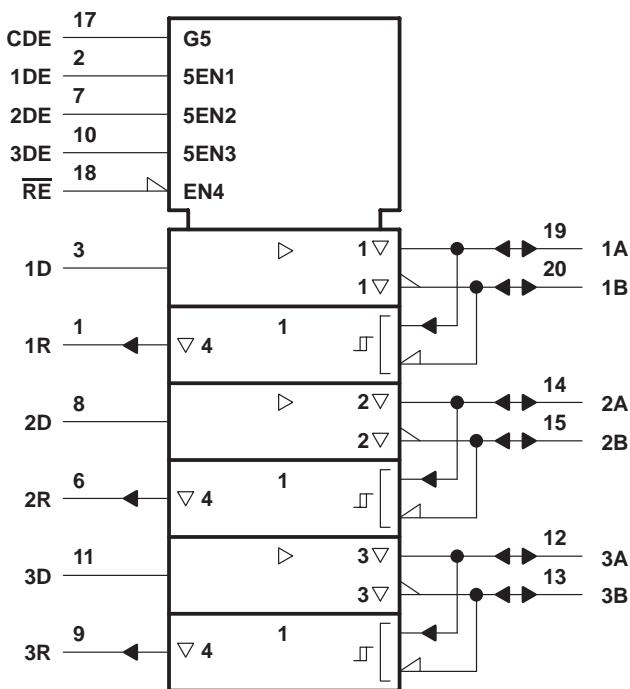
DIFFERENTIAL INPUTS A-B	ENABLE RE	OUTPUT R
$V_{ID} \geq 0.3 \text{ V}$	L	H
$-0.3 \text{ V} < V_{ID} < 0.3 \text{ V}$	L	?
$V_{ID} \leq -0.3 \text{ V}$	L	L
X	H	Z
Open	L	H

H = high level, L = low level, ? = indeterminate, X = irrelevant,  
Z = high impedance (off)

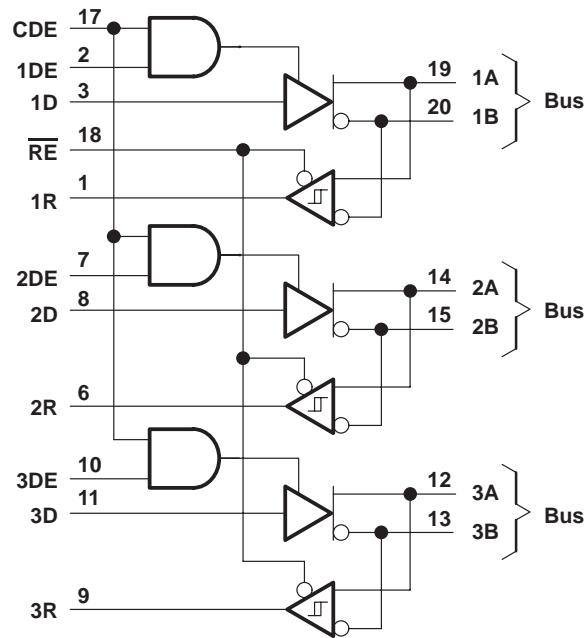
### AVAILABLE OPTIONS

SKEW LIMIT	PART NUMBER	
10 ns	SN75ALS171DW	SN75ALS171J
5 ns	SN75ALS171ADW	

logic symbol<sup>†</sup>

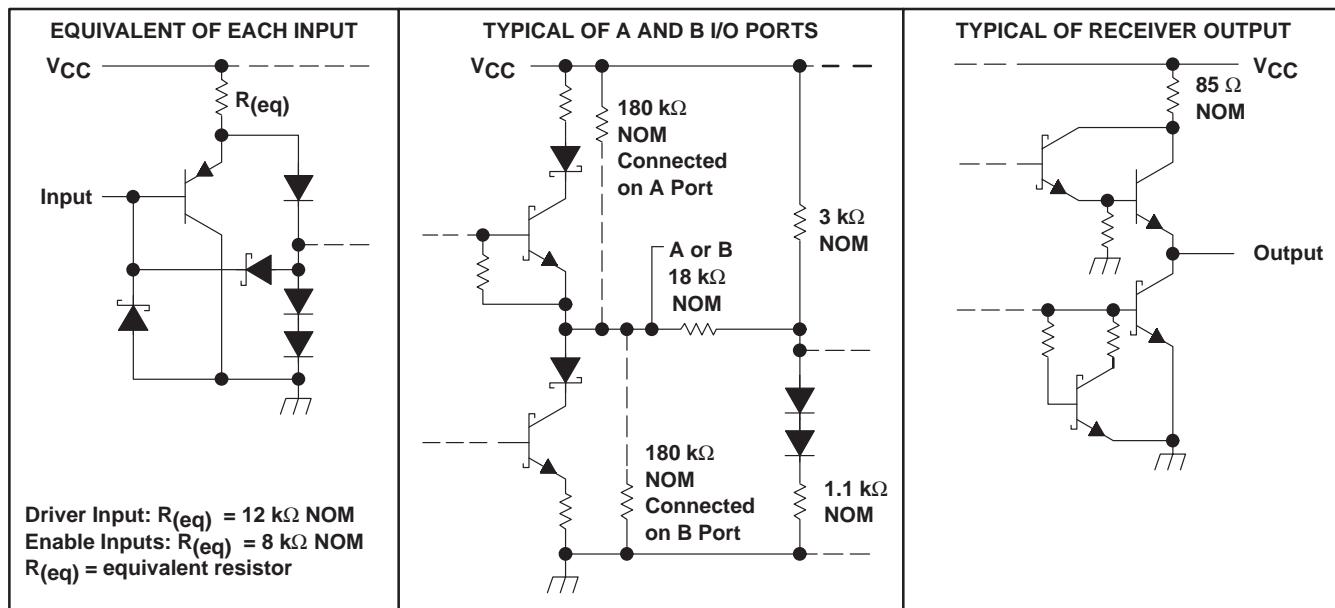


logic diagram (positive logic)



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

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## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage, $V_{CC}$ (see Note 1) .....	7 V
Voltage range at any bus terminal .....	-7 V to 12 V
Enable input voltage, $V_I$ .....	7 V
Continuous total power dissipation .....	See Dissipation Rating Table
Operating free-air temperature range, $T_A$ .....	0°C to 70°C
Storage temperature range, $T_{STG}$ .....	-65°C to 150°C
Lead temperature 1.6 mm (1/16 inch) from case for 10 seconds: DW package .....	260°C
Lead temperature 1.6 mm (1/16 inch) from case for 60 seconds: J package .....	300°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING
DW	1125 mW	9.0 mW/°C	720 mW
J	1025 mW	8.2 mW/°C	656 mW

## recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, $V_{CC}$		4.75	5	5.25	V
Voltage at any bus terminal (separately or common mode), $V_I$ or $V_{IC}$		-7		12	V
High-level input voltage, $V_{IH}$	D, CDE, DE, and $\overline{RE}$	2			V
Low-level input voltage, $V_{IL}$	D, CDE, DE, and $\overline{RE}$			0.8	V
Differential input voltage, $V_{ID}$ (see Note 2)				$\pm 12$	V
High-level output current, $I_{OH}$	Driver			-60	mA
	Receiver			-400	$\mu\text{A}$
Low-level output current, $I_{OL}$	Driver			60	mA
	Receiver			8	
Operating free-air temperature, $T_A$		0		70	$^\circ\text{C}$

NOTE 2: Differential-input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS <sup>†</sup>		MIN	TYP <sup>‡</sup>	MAX	UNIT
$V_{IK}$	Input clamp voltage	$I_I = -18 \text{ mA}$			-1.5	V
$V_O$	Output voltage	$I_O = 0$	0	6	6	V
$V_{OH}$	High-level output voltage	$V_{CC} = 4.75 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OH} = -55 \text{ mA}$	2.7			V
$V_{OL}$	Low-level output voltage	$V_{CC} = 4.75 \text{ V}$ , $V_{IL} = 0.8 \text{ V}$ , $I_{OL} = 55 \text{ mA}$		1.7	1.7	V
$ \Delta V_{OD} $	Differential output voltage	$I_O = 0$	1.5	6	6	V
$ \Delta V_{OD} $	Differential output voltage	$R_L = 100 \Omega$ , See Figure 1	$1/2 V_{OD1}$ or 2 <sup>§</sup>	2.5	5	V
		$R_L = 54 \Omega$ , See Figure 1	1.5	2.5	5	
$V_{OD3}$	Differential output voltage	$V_{test} = -7 \text{ V}$ to $12 \text{ V}$ , See Figure 2	1.5	5	5	V
$\Delta V_{OD1}$	Change in magnitude of differential output voltage <sup>¶</sup>	$R_L = 54 \Omega$ or $100 \Omega$ , See Figure 1			$\pm 0.2$	V
$V_{OC}$	Common-mode output voltage				3	V
$\Delta V_{OC1}$	Change in magnitude of common-mode output voltage <sup>¶</sup>				-1	V
$\Delta V_{OC2}$					$\pm 0.2$	V
$I_O$	Output current	$V_O = 12 \text{ V}$		1		mA
		$V_O = -7 \text{ V}$			-0.8	
$I_{IH}$	High-level enable-input current	$D$ and $DE$		20		$\mu\text{A}$
		$CDE$	$V_{IH} = 2.7 \text{ V}$		60	
$I_{IL}$	Low-level enable-input current	$D$ and $DE$			-100	
		$CDE$	$V_{IL} = 0.4 \text{ V}$		-900	
$I_{OS}$	Short-circuit output current	$V_O = -6 \text{ V}$			-250	mA
		$V_O = 0$			-150	
		$V_O = V_{CC}$			250	
		$V_O = 8 \text{ V}$			250	
$I_{CC}$	Supply current	No load	Outputs enabled	69	90	mA
			Outputs disabled	57	78	

<sup>†</sup> The power-off measurement in ANSI Standard EIA/TIA-422-B applies to disabled outputs only and is not applied to combined inputs and outputs.

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^\circ\text{C}$ .

<sup>§</sup> The minimum  $V_{OD2}$  with  $100\text{-}\mu\text{A}$  load is either  $1/2 V_{OD2}$  or  $2 \text{ V}$ , whichever is greater.

<sup>¶</sup>  $|\Delta V_{OD}|$  and  $|\Delta V_{OC}|$  are the changes in magnitude of  $V_{OD}$  and  $V_{OC}$ , respectively, that occur when the input is changed from a high level to a low level.

NOTE 3: This applies for both power on and off; refer to EIA Standard RS-485 for exact conditions. The EIA/TIA-422-B limit does not apply for a combined driver and receiver terminal.

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

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**switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT		
t <sub>d</sub> (OD)	ALS171	R <sub>L</sub> = 54 Ω, C <sub>L</sub> = 50 pF	3	13		ns		
		See Figure 3,	6	11				
	ALS171A	R <sub>L1</sub> = R <sub>L3</sub> = 165 Ω, C <sub>L</sub> = 60 pF, R <sub>L2</sub> = 75 Ω,	3	13				
		See Figure 6	6	11				
t <sub>sk(p)</sub>	Pulse skew‡		R <sub>L</sub> = 54 Ω, C <sub>L</sub> = 50 pF, See Figure 3	1	5	ns		
			R <sub>L1</sub> = R <sub>L3</sub> = 165 Ω, C <sub>L</sub> = 60 pF,	R <sub>L2</sub> = 75 Ω, See Figure 6	1	5	ns	
t <sub>sk(lim)</sub>	ALS171	R <sub>L</sub> = 54 Ω, See Figure 3	C <sub>L</sub> = 50 pF,	10		ns		
		See Figure 6		5				
	ALS171A	R <sub>L1</sub> = R <sub>L3</sub> = 165 Ω, C <sub>L</sub> = 60 pF,	R <sub>L2</sub> = 75 Ω,	10				
		See Figure 6		5				
t <sub>t(OD)</sub>	Differential-output transition time		R <sub>L</sub> = 54 Ω, See Figure 3	C <sub>L</sub> = 50 pF,	3	8	13	ns
			R <sub>L1</sub> = R <sub>L3</sub> = 165 Ω, C <sub>L</sub> = 60 pF,	R <sub>L2</sub> = 75 Ω, V <sub>TERM</sub> = 5 V, See Figure 6	3	8	13	
t <sub>PZH</sub>	Output enable time to high level	R <sub>L</sub> = 110 Ω,	See Figure 4		30	50	ns	
t <sub>PZL</sub>	Output enable time to low level	R <sub>L</sub> = 110 Ω,	See Figure 5		30	50	ns	
t <sub>PHZ</sub>	Output disable time from high level	R <sub>L</sub> = 110 Ω,	See Figure 4		3	8	13	ns
t <sub>PLZ</sub>	Output disable time from low level	R <sub>L</sub> = 110 Ω,	See Figure 5		3	8	13	ns
t <sub>PDE</sub>	Differential-output enable time	R <sub>L1</sub> = R <sub>L3</sub> = 165 Ω,	R <sub>L2</sub> = 75 Ω,	8	30	45	ns	
t <sub>PDZ</sub>	Differential-output disable time	C <sub>L</sub> = 60 pF,	See Figure 7		5	10	45	ns

† All typical values are at V<sub>CC</sub> = 5 V and T<sub>A</sub> = 25°C.

‡ Pulse skew is defined as the |t<sub>d</sub>(ODH) – t<sub>d</sub>(ODL)| of each channel.

§ Skew limit is the maximum difference in propagation delay times between any two channels of one device and between any two devices. This parameter is applicable at one V<sub>CC</sub> and operating temperature within the recommended operating conditions.

## SYMBOL EQUIVALENTS

DATA-SHEET PARAMETER	EIA/TIA-422-B	RS-485
V <sub>O</sub>	V <sub>oa</sub> , V <sub>ob</sub>	V <sub>oa</sub> , V <sub>ob</sub>
V <sub>OD1</sub>	V <sub>O</sub>	V <sub>O</sub>
V <sub>OD2</sub>	V <sub>t</sub> (R <sub>L</sub> = 100 Ω)	V <sub>t</sub> (R <sub>L</sub> = 54 Ω)
V <sub>OD3</sub>		V <sub>t</sub> (Test Termination Measurement 2)
V <sub>test</sub>		V <sub>tst</sub>
Δ V <sub>OD</sub>	V <sub>t</sub>   –  V <sub>t</sub>	V <sub>t</sub>   –  V <sub>t</sub>
V <sub>OC</sub>	V <sub>os</sub>	V <sub>os</sub>
Δ V <sub>OC</sub>	V <sub>os</sub> – V <sub>os</sub>	V <sub>os</sub> – V <sub>os</sub>
I <sub>OS</sub>	I <sub>sa</sub>   ,   I <sub>sb</sub>	
I <sub>O</sub>	I <sub>xa</sub>   ,   I <sub>xb</sub>	I <sub>ia</sub> , I <sub>ib</sub>

## RECEIVER SECTION

**electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$V_{IT+}$	Positive-going input threshold voltage	$V_O = 2.7 \text{ V}$ , $I_O = -0.4 \text{ mA}$			0.3	V
$V_{IT-}$	Negative-going input threshold voltage	$V_O = 0.5 \text{ V}$ , $I_O = 8 \text{ mA}$	-0.3‡			V
$V_{hys}$	Hysteresis voltage ( $V_{IT+} - V_{IT-}$ )			60		mV
$V_{IK}$	Enable-input clamp voltage	$I_I = -18 \text{ mA}$			-1.5	V
$V_{OH}$	High-level output voltage	$V_{ID} = 300 \text{ mV}$ , See Figure 8	$I_{OH} = -400 \mu\text{A}$ ,	2.7		V
$V_{OL}$	Low-level output voltage	$V_{ID} = -300 \text{ mV}$ , See Figure 8	$I_{OL} = 8 \text{ mA}$ ,		0.45	V
$I_{OZ}$	High-impedance-state output current	$V_O = 0.4 \text{ V}$ to $2.4 \text{ V}$			$\pm 20$	$\mu\text{A}$
$I_I$	Line input current	Other input = 0 V, See Note 4	$V_I = 12 \text{ V}$		1	mA
			$V_I = -7 \text{ V}$		-0.8	
$I_{IH}$	High-level enable-input current	$V_{IH} = 2.7 \text{ V}$			60	$\mu\text{A}$
$I_{IL}$	Low-level enable-input current	$V_{IL} = 0.4 \text{ V}$			-300	$\mu\text{A}$
$r_I$	Input resistance				12	$\text{k}\Omega$
$I_{OS}$	Short-circuit output current	$V_{ID} = 300 \text{ mV}$ ,	$V_O = 0$	-15	-85	mA
$I_{CC}$	Supply current	No load	Outputs enabled	69	90	mA
			Outputs disabled	57	78	

† All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^\circ\text{C}$ .

‡ The algebraic convention, in which the less positive (more negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 4: This applies for both power on and off; refer to EIA Standard RS-485 for exact conditions.

**switching characteristics over recommended ranges of supply voltage and operating free-air temperature range**

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
$t_{PLH}$	Propagation delay time, low- to high-level output	ALS171	$V_{ID} = -1.5 \text{ V}$ to $1.5 \text{ V}$ , $C_L = 15 \text{ pF}$ , $T_A = 25^\circ\text{C}$ , See Figure 9	9	19	ns
		ALS171A		11	16	
$t_{PHL}$	Propagation delay time, high- to low-level output	ALS171		9	19	ns
		ALS171A		11	16	
$t_{sk(p)}$	Pulse skew§	ALS171	$V_{ID} = -1.5 \text{ V}$ to $1.5 \text{ V}$ , $C_L = 15 \text{ pF}$ , See Figure 9	2	5	ns
$t_{sk(lim)}$	Skew limit¶				10	
		ALS171A			5	
$t_{PZH}$	Output enable time to high level		$C_L = 15 \text{ pF}$ , See Figure 10	7	14	ns
$t_{PZL}$	Output enable time to low level			7	14	
$t_{PHZ}$	Output disable time from high level		$C_L = 15 \text{ pF}$ , See Figure 10	20	35	ns
$t_{PLZ}$	Output disable time from low level			8	17	

† All typical values are at  $V_{CC} = 5 \text{ V}$  and  $T_A = 25^\circ\text{C}$ .

§ Pulse skew is defined as the  $|t_{PLH} - t_{PHL}|$  of each channel.

¶ Skew limit is the maximum difference in propagation delay times between any two channels of one device and between any two devices. This parameter is applicable at one  $V_{CC}$  and operating temperature within the recommended operating conditions.

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

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## PARAMETER MEASUREMENT INFORMATION

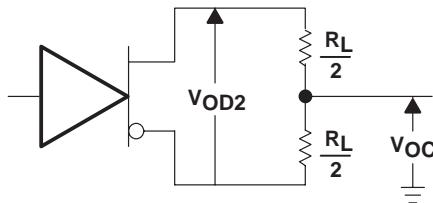


Figure 1. Driver  $V_{OD}$  and  $V_{OC}$

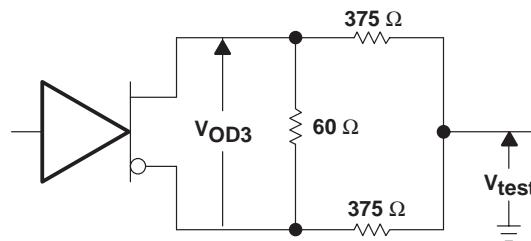
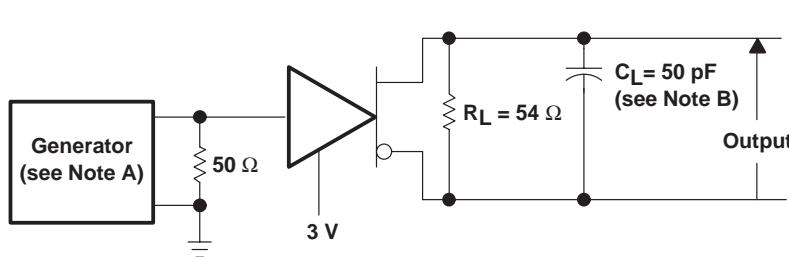
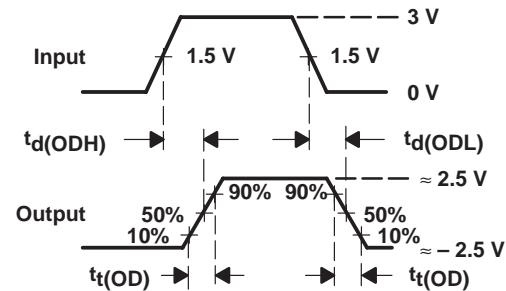


Figure 2. Driver  $V_{OD3}$



TEST CIRCUIT

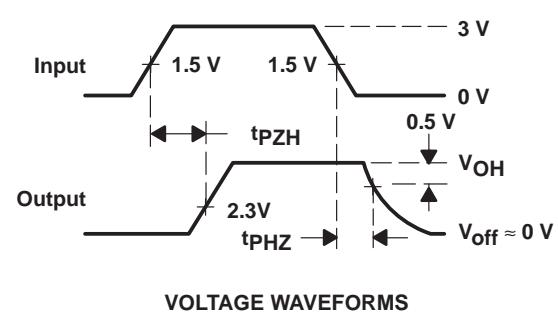
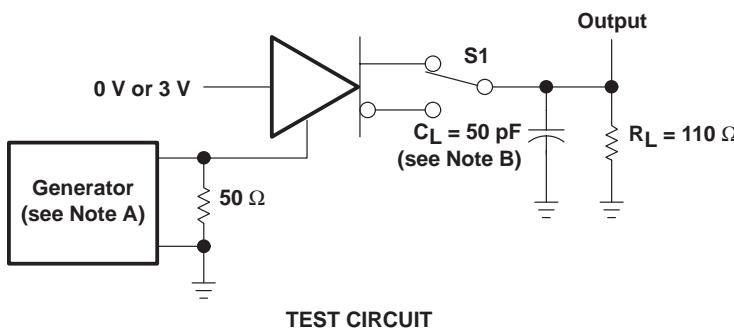


VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

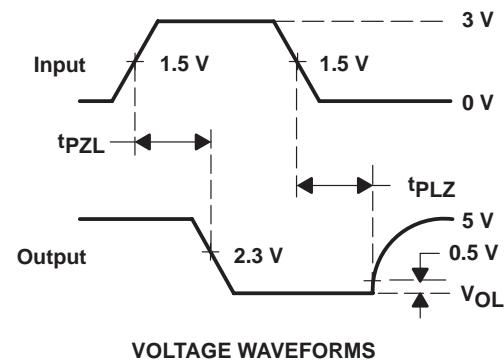
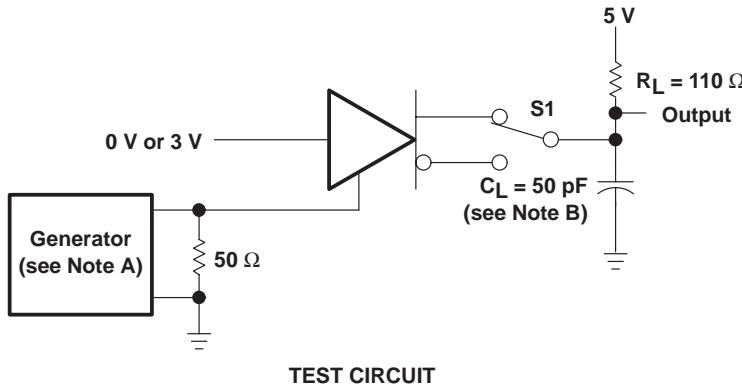
Figure 3. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50 \Omega$ .  
B.  $C_L$  includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms



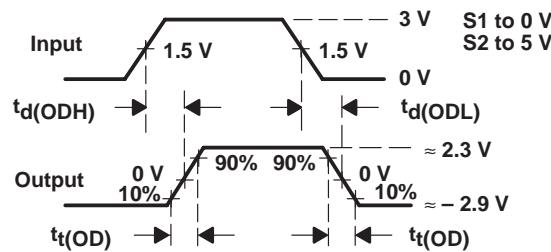
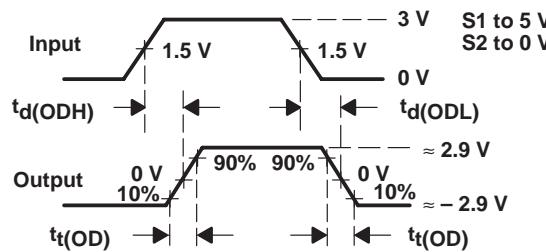
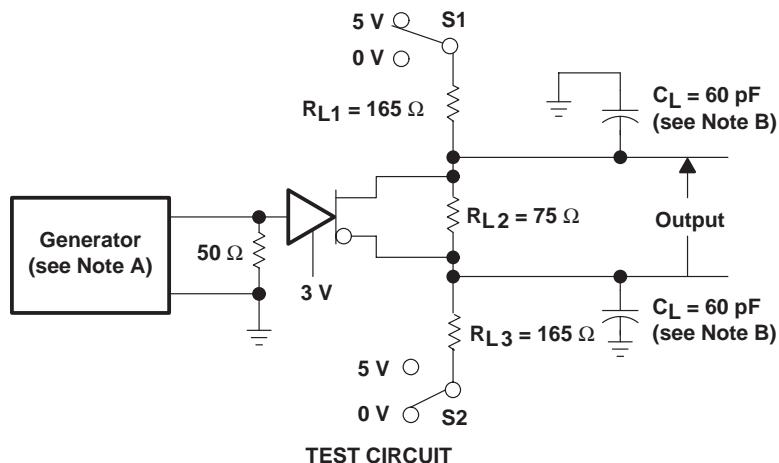
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq$  1 MHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50 \Omega$ .  
B.  $C_L$  includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

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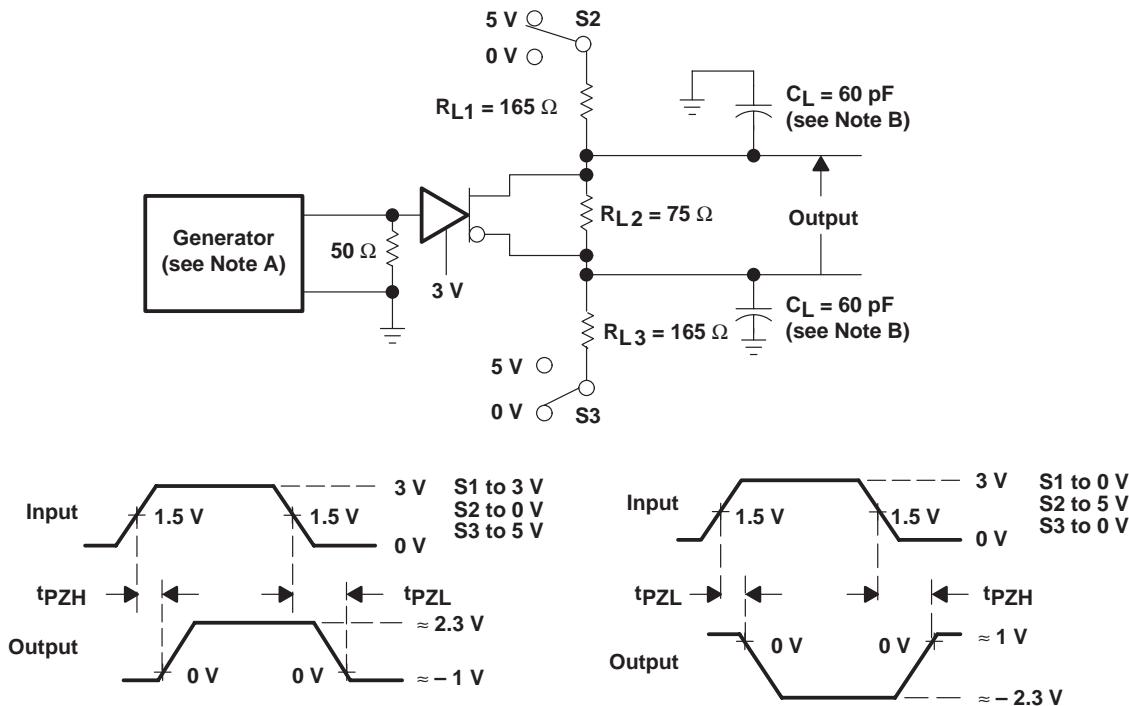
## PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics:  $PRR \leq 1 \text{ MHz}$ , 50% duty cycle,  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 6. Driver Test Circuit and Voltage Waveforms  
With Double-Differential-SCSI Termination for the Load

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq 1$  MHz, 50% duty cycle,  $t_r \leq 6$  ns,  $t_f \leq 6$  ns,  $Z_O = 50\ \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 7. Driver Differential-Enable and Disable Times With a Double-SCSI Termination

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

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## PARAMETER MEASUREMENT INFORMATION

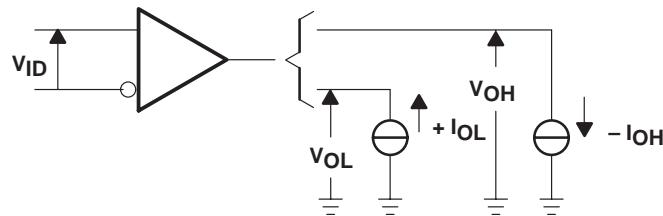
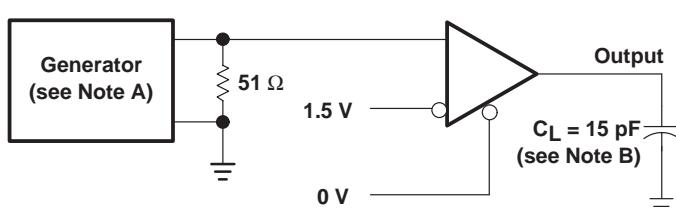
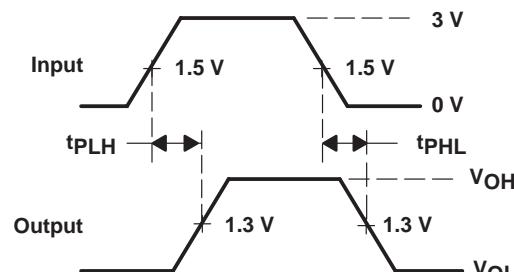


Figure 8. Receiver  $V_{OH}$  and  $V_{OL}$



TEST CIRCUIT

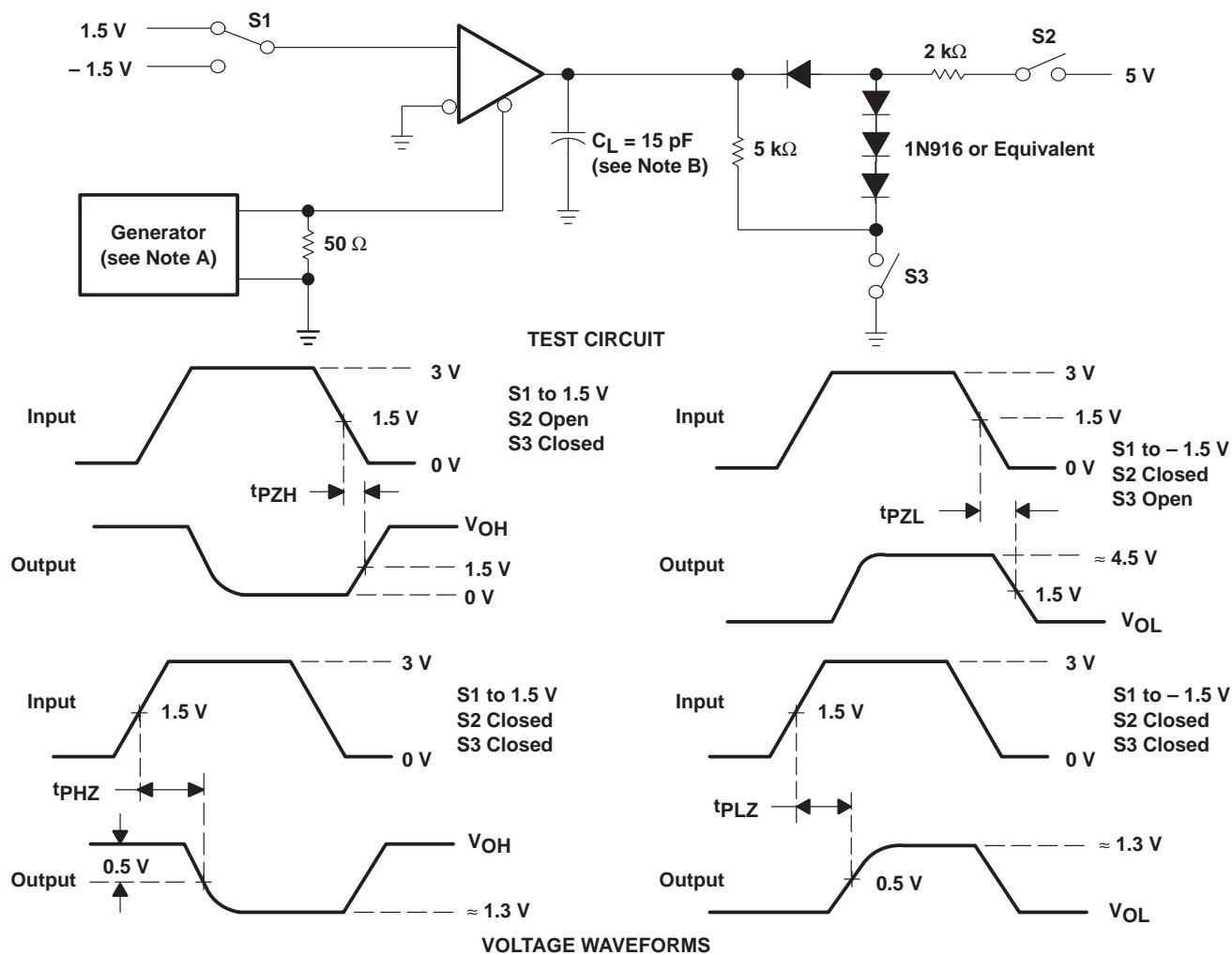


VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics:  $PRR \leq 1 \text{ MHz}$ , 50% duty cycle,  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 9. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR  $\leq 1 \text{ MHz}$ , 50% duty cycle,  $t_r \leq 6 \text{ ns}$ ,  $t_f \leq 6 \text{ ns}$ ,  $Z_O = 50 \Omega$ .  
 B.  $C_L$  includes probe and jig capacitance.

Figure 10. Receiver Test Circuit and Voltage Waveforms

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

SLLS056D – AUGUST 1987 – REVISED SEPTEMBER 1995

## TYPICAL CHARACTERISTICS

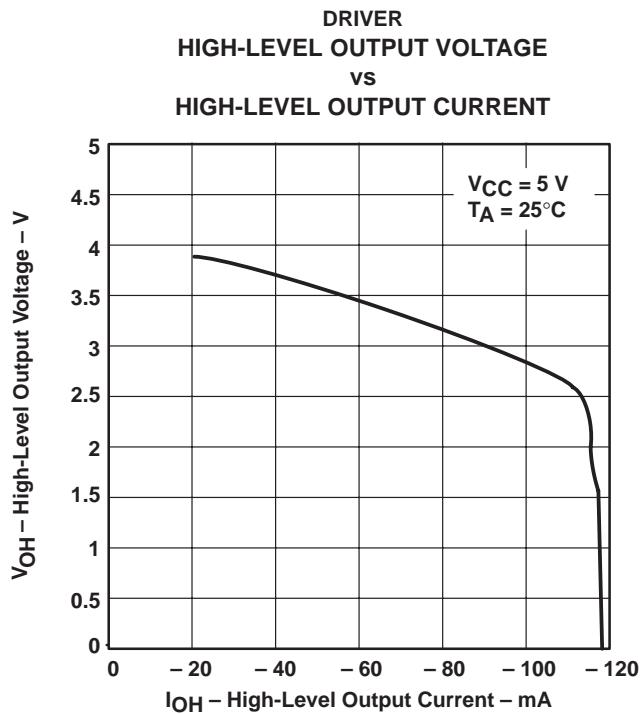


Figure 11

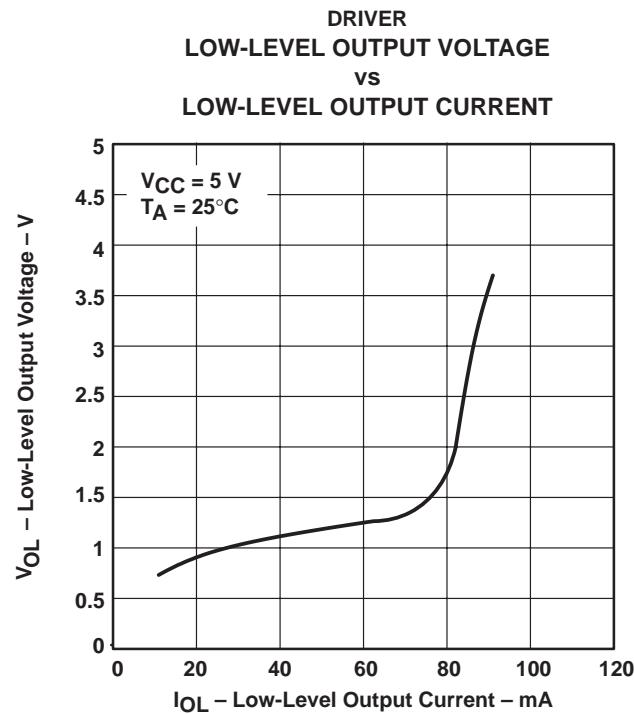


Figure 12

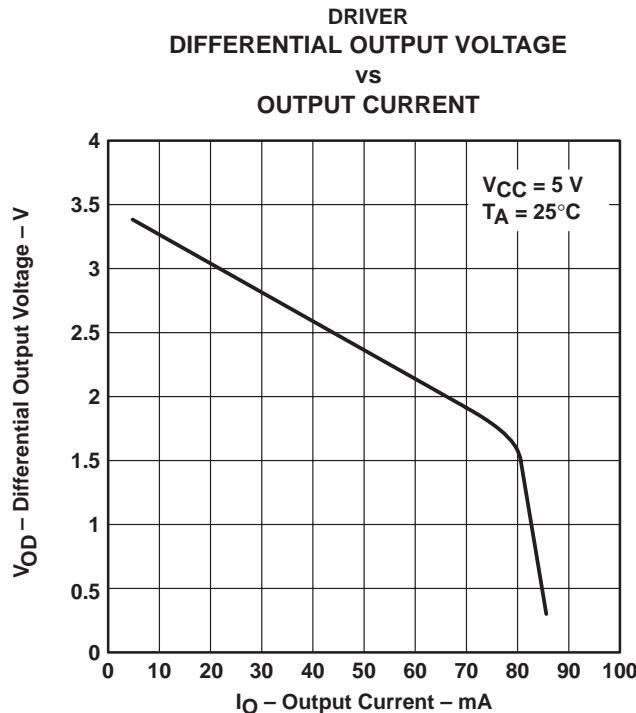


Figure 13

TYPICAL CHARACTERISTICS

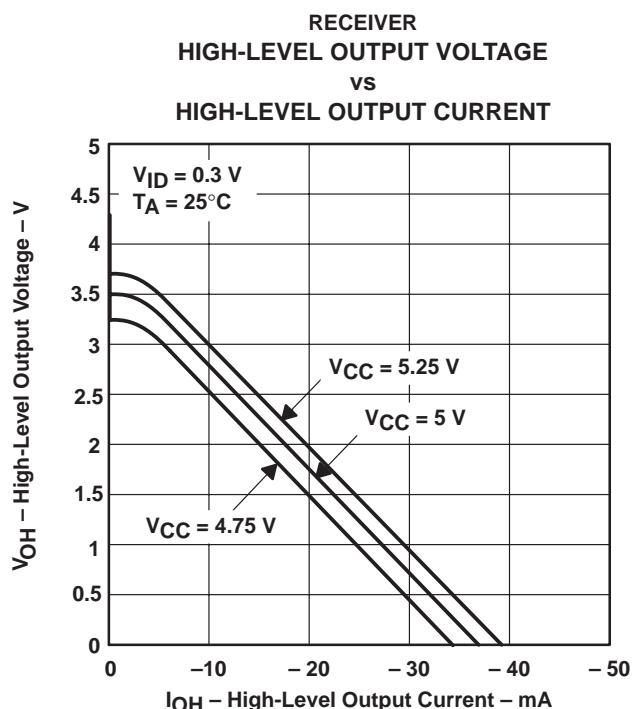


Figure 14

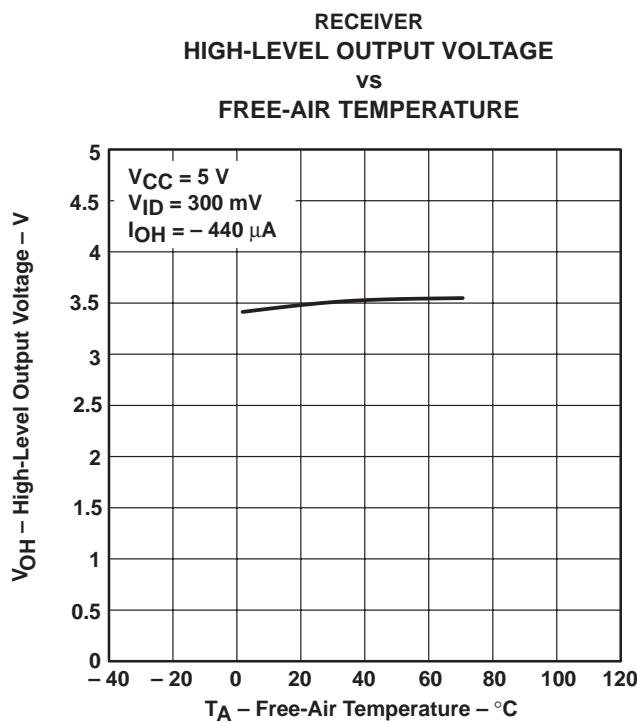


Figure 15

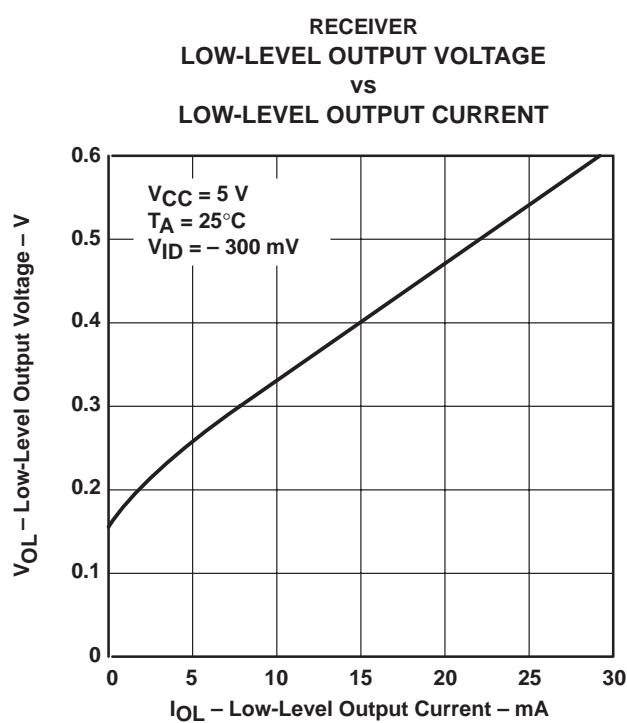


Figure 16

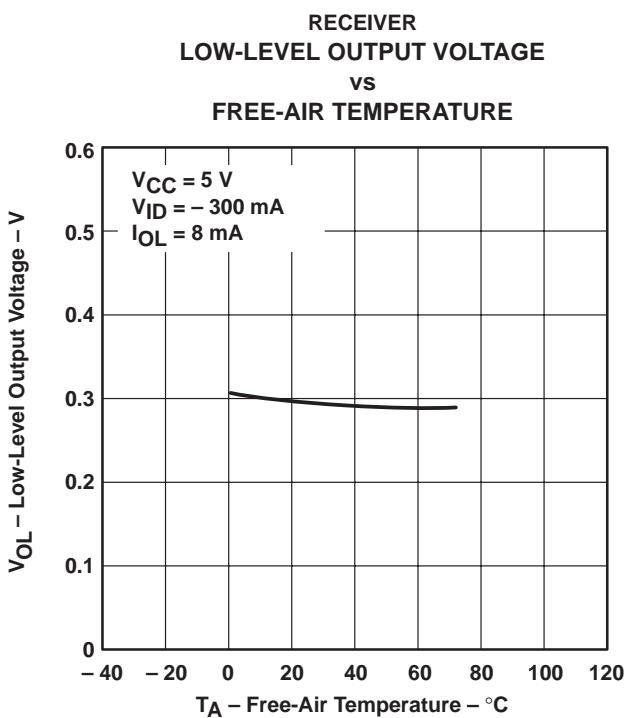


Figure 17

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

SLLS056D – AUGUST 1987 – REVISED SEPTEMBER 1995

## TYPICAL CHARACTERISTICS

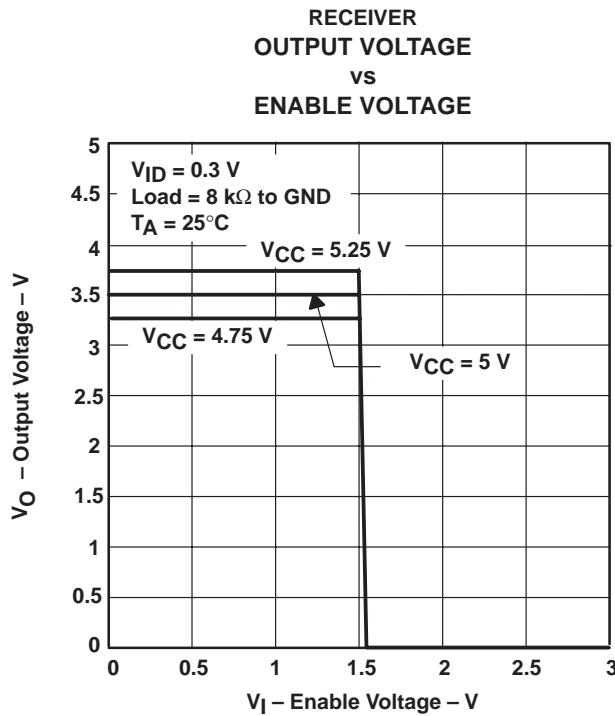


Figure 18

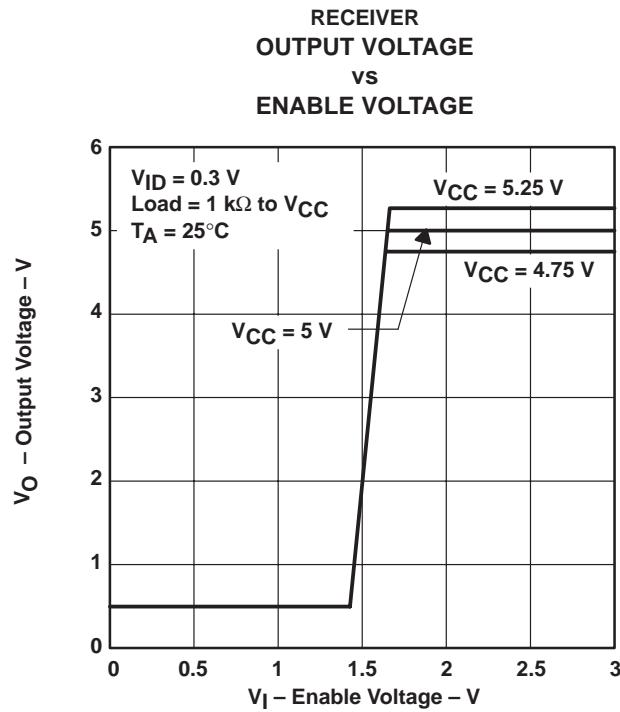
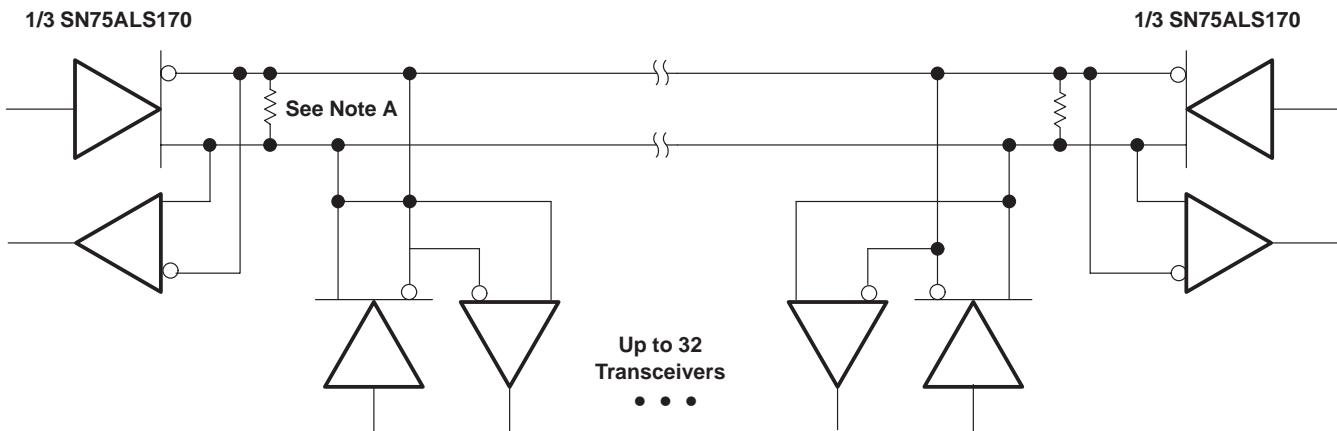


Figure 19

APPLICATION INFORMATION



NOTE A: The line should be terminated at both ends in its characteristic impedance. Stub lengths off the main line should be kept as short as possible.

Figure 20. Typical Application Circuit

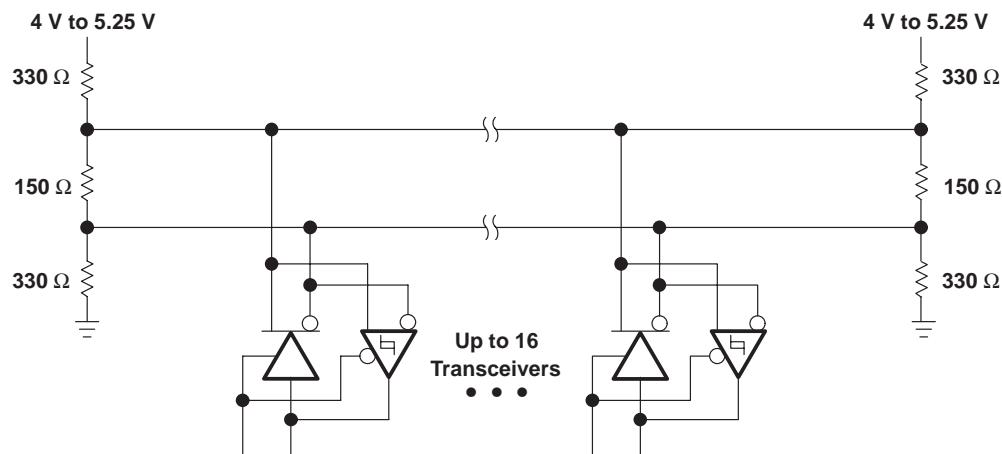


Figure 21. Typical Differential SCSI Application Circuit

# SN75ALS171, SN75ALS171A TRIPLE DIFFERENTIAL BUS TRANSCEIVERS

SLLS056D – AUGUST 1987 – REVISED SEPTEMBER 1995

## APPLICATION INFORMATION

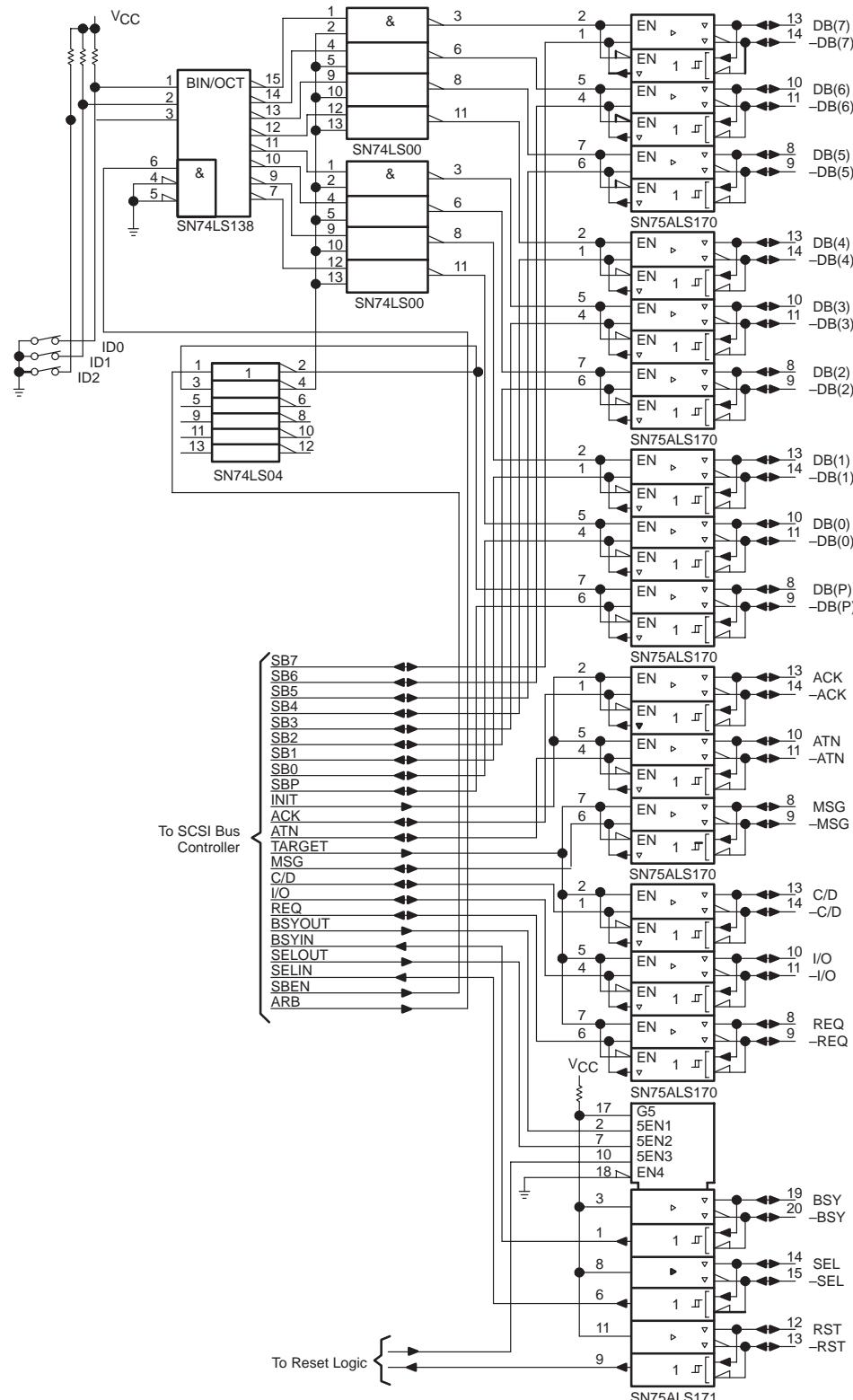


Figure 22. Typical Differential SCSI Bus Interface Implementation

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN75ALS171ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS171J	OBsolete	CDIP	J	20		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

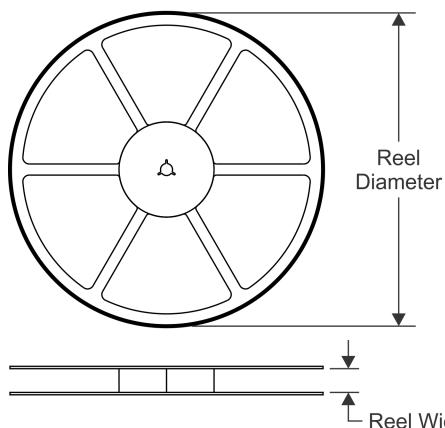
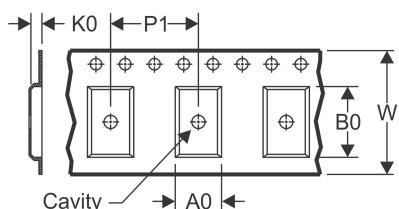
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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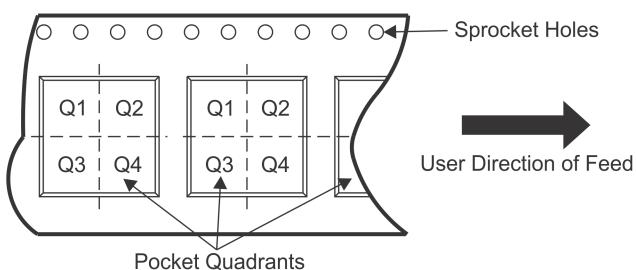
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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS171ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75ALS171DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

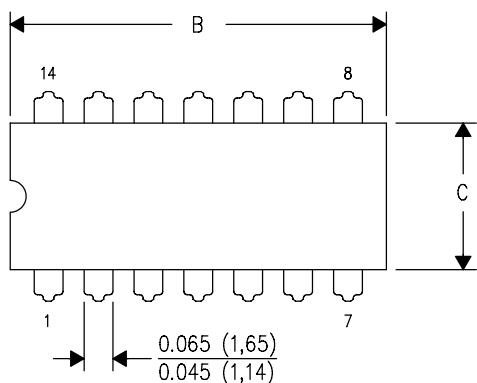
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS171ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN75ALS171DWR	SOIC	DW	20	2000	367.0	367.0	45.0

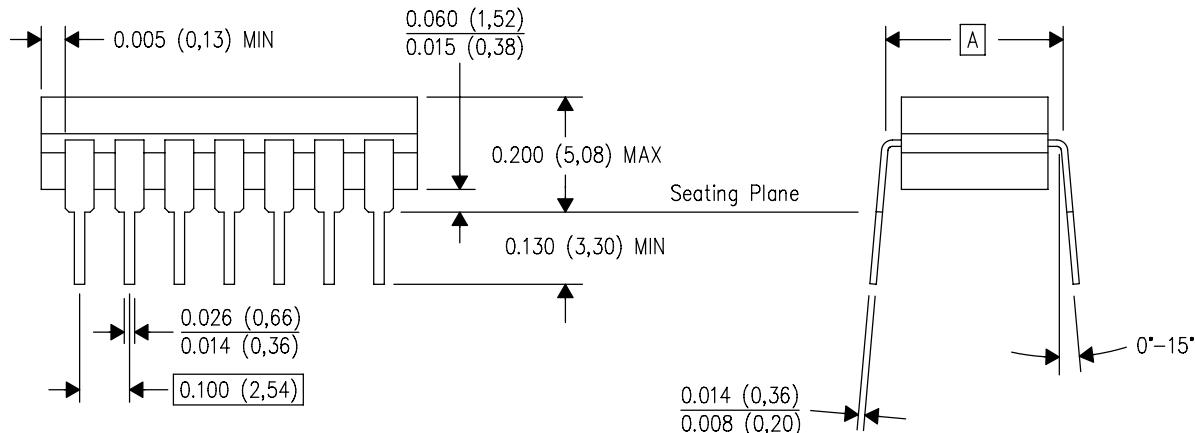
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

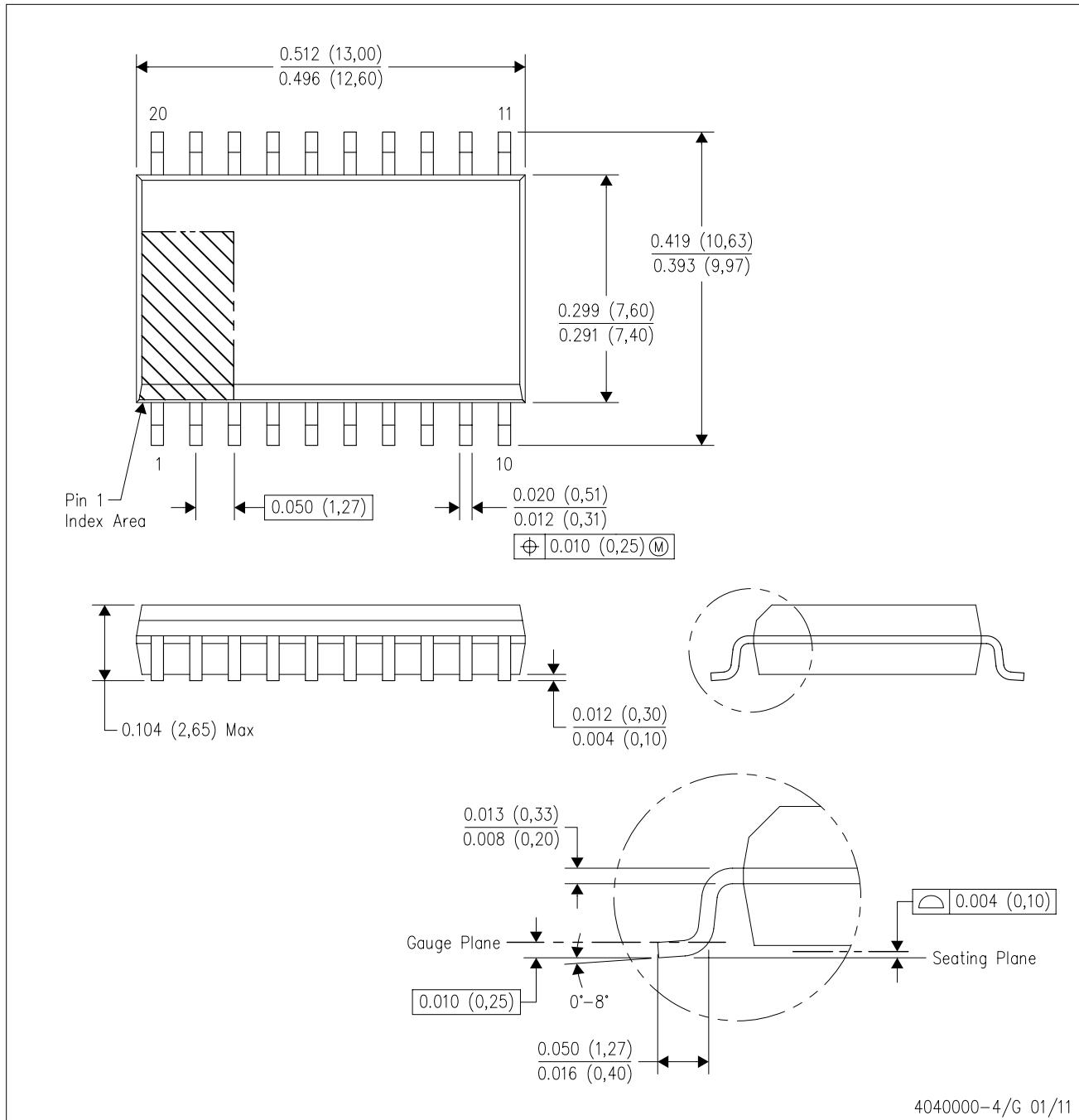


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

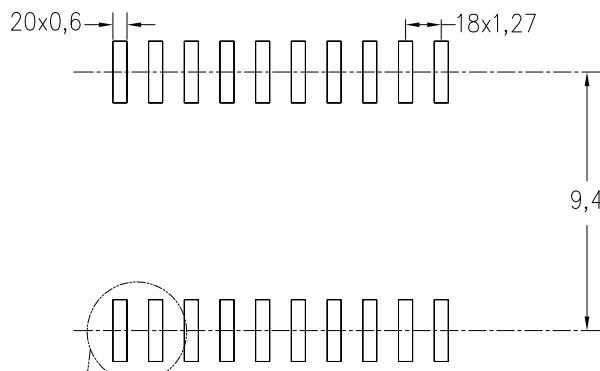
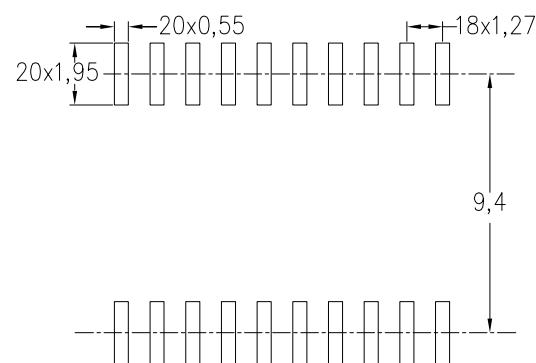


NOTES:

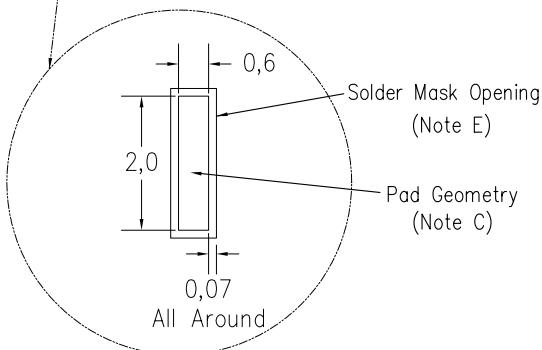
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0.15).
- Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

Example Board Layout  
(Note C)Stencil Openings  
(Note D)

Non Solder Mask Define Pad



4209202-4/E 07/11

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Refer to IPC7351 for alternate board design.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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